

		<b>Material Composition Declaration</b> Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.					
1752-2 1.1		IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>		<b>Form Type *</b> <b>Distribute</b>		<b>Declaration Class *</b> <b>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information</b>			
<b>Supplier Information</b>									
<b>Company Name *</b> <b>National Semiconductor</b>		Company Unique ID NATSEMI		Unique ID Authority 04-147-2986		<b>Response Date *</b> 11-11-2011		Response Document ID	
Contact Name * Lorena Dudman		Title - Contact Product Stewardship Eng.		Phone - Contact * 1-408-721-8180		Email - Contact * Green.Project@nsc.com			
Authorized Representative * Lorena Dudman		Title - Representative Product Stewardship Eng.		Phone - Representative * 1-408-721-8180		Email - Representative * Green.Project@nsc.com		Supplier Comments or URL for Additional Information <a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>	
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	<b>Weight *</b>	UOM	Unit Type
		DS32EL0421SQX NOPB	DS32EL0421SQX NOPB	11-11-2011			<b>123.19</b>	mg	Each
	Alternate Recommendation				Alternate Item Comments				
<b>Manufacturing Process Information</b>									
Terminal Plating / Grid Array Material		Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles	
<b>Sn</b>		<b>CU Alloy</b>	<b>3</b>	<b>260 C</b>		<b>40 seconds</b>		<b>4</b>	
<b>Comments</b>									
<b>"Does not contain PFOS."</b>									

<b>RoHS Material Type Declaration</b>	<b>Declaration Type * Custom</b>
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<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium</b>
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-I.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION

<b>RoHS Declaration *</b> 1 - Item(s) does not contain RoHS restricted substances per the definition above	<b>Supplier Acceptance *</b>	<b>Accepted</b>
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration and above and choose all applicable exemptions.

<b>Declaration Signature</b>	
<b>Supplier Signature</b>	 John L. Conn Vice President Quality
	<b>John L. Conn Vice President Quality</b>

## Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance	PPM
	Chip	9.251	mg	Requester		Si	7440-21-3		9.195	mg		994,000
				Requester		Al	7429-90-5		0.056	mg		6,000
	Plastic	55.960	mg	Requester		SiO2	60676-86-0		50.644	mg		905,000
				Requester		Epoxy Resin	25928-94-3		5.316	mg		95,000
	Leadframe	50.160	mg	Requester		Cu	7440-50-8		48.254	mg		962,000
				Requester		Ni	7440-02-0		1.505	mg		30,000
				Requester		Si	7440-21-3		0.326	mg		6,500
				Requester		Mg	7439-95-4		0.075	mg		1,500
	Ext. LeadFinish	3.430	mg	Requester		Sn	7440-31-5		3.430	mg		1,000,000
	Die Attach	2.045	mg	Requester		Ag	7440-22-4		1.534	mg		750,000
				Requester		Epoxy Resin	25928-94-3		0.511	mg		250,000
	Wires	1.374	mg	Requester		Au	7440-57-5		1.374	mg		1,000,000
	Int. LeadFinish	0.971	mg	Requester		Ag	7440-22-4		0.971	mg		1,000,000